

ABSTRACT OF THE DISCLOSURE

A semiconductor laser package includes an island member formed of metal, including a base plane and a block member protruding in a direction substantially perpendicular to the base plane, a lead, a resin member molded integrally with the island member and the lead so as to fix the relative position relationship between the island member and the lead, a laser chip fixed at the block member, and a light receiving element functioning as a light receiving unit, directly fixed to the resin member.